## 2SK3547G

## Silicon N-channel MOSFET

#### For switching

#### ■ Features

- High-speed switching
- Wide frequency band
- Gate-protection diode built-in

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Drain-source voltage	V <sub>DS</sub>	50	V	
Gate-source voltage (Drain open)	$V_{GSO}$	±7	V	
Drain current	$I_{\mathrm{D}}$	100	mA	
Peak drain current	$I_{DP}$	200	mA	
Power dissipation	$P_{\mathrm{D}}$	100	mW	
Channel temperature	$T_{ch}$	125	°C	
Storage temperature	T <sub>stg</sub>	-55 to +125	°C	

#### Package

Code

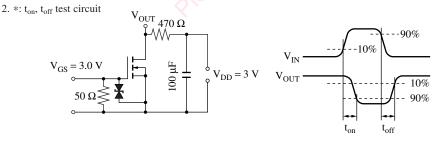
SSSMini3-F2

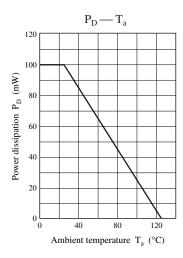
- Marking Symbol: 5F
- Pin Name
  - 1: Gate
  - 2: Source
- 3: Drain

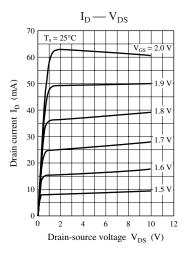
### ■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

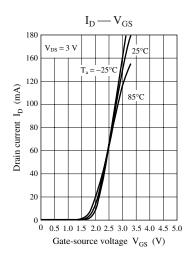
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Drain-source surrender voltage	V <sub>DSS</sub>	$I_D = 10  \mu A,  V_{GS} = 0$	50	.0	5	V
Drain-source cutoff current	$I_{DSS}$	$V_{DS} = 50 \text{ V}, V_{GS} = 0$	4	0.	1.0	μΑ
Gate-source cutoff current	$I_{GSS}$	$V_{GS} = \pm 7 \text{ V}, V_{DS} = 0$		· . c	±5.0	μΑ
Gate threshold voltage	V <sub>th</sub>	$I_D = 1.0 \mu\text{A},  V_{DS} = 3  \text{V}$	0.9	1.2	1.5	V
Drain-source ON resistance	R <sub>DS(on)</sub>	$I_D = 10 \text{ mA}, V_{GS} = 2.5 \text{ V}$	0.	8	15	Ω
		$I_D = 10 \text{ mA}, V_{GS} = 4.0 \text{ V}$		6	12	
Forward transfer admittance	Y <sub>fs</sub>	$I_D = 10 \text{ mA}, V_{DS} = 3 \text{ V}, f = 1 \text{ kHz}$	20	60		mS
Short-circuit forward transfer capacitance (Common-source)	C <sub>iss</sub>	$V_{DS} = 3 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$		12		pF
Short-circuit output capacitance (Common-source)	C <sub>oss</sub>	$V_{DS} = 3 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$		7		pF
Reverse transfer capacitance (Common-source)	C <sub>rss</sub>	$V_{DS} = 3 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$		3		pF
Turn-on time *	t <sub>on</sub>	$V_{DD} = 3 \text{ V}, V_{GS} = 0 \text{ V to } 3 \text{ V}, R_L = 470 \Omega$		200		ns
Turn-off time *	t <sub>off</sub>	$V_{DD} = 3 \text{ V}, V_{GS} = 3 \text{ V to } 0 \text{ V}, R_L = 470 \Omega$		200		ns

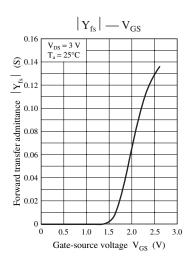
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

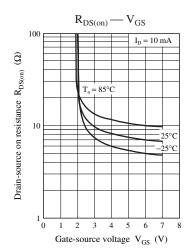








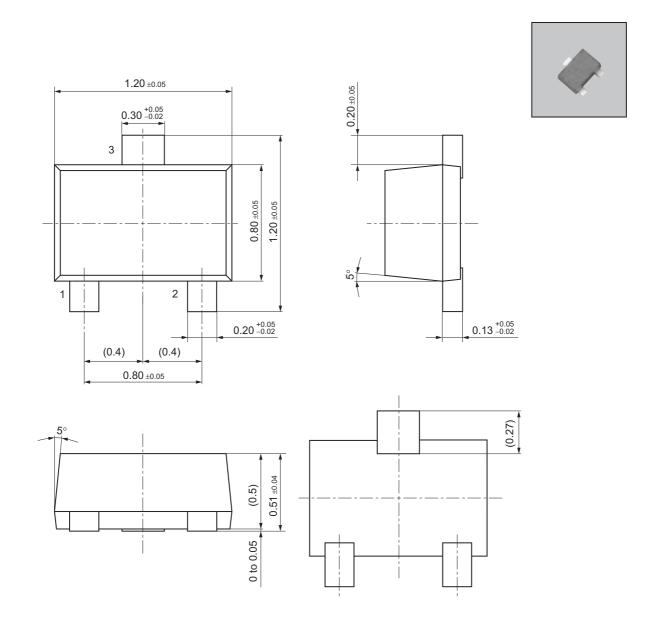




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## SSSMini3-F2

Unit: mm



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